1	Method Article
2	Rapid chemical bath deposition and optical property of
3	CuS films using sodium ethylenediamine tetraacetate as
4	chelating agent
5	Abstract: CuS films were fabricated by a chemical bath deposition process in an
6	aqueous solution of cupric acetate, thiourea, and different contents of sodium
7	ethylenediamine tetraacetate (EDTA-2Na) with different contents at 50 °C. The
8	films were characterized by X-ray diffraction, atomic force microscopy,
9	ultraviolet-visible spectrophotometry and photoluminescence spectrophotometry. The
10	effects of EDTA-2Na content and deposition time on the deposition rate, thickness,
11	transmittance, band gap energy, and photoluminescence of the films were
12	investigated. The films were fast deposited with this method. Molar ratio of
13	EDTA-2Na/Cu ²⁺ =1.0 led to fastest deposition. The band gap energy of the films is
14	in the ranged-from of 2.59-2.92 eV. The films showed broad emission centered at
15	~443 nm. The emission intensity decreased with increasing deposition time.
16	Keywords: CuS; film; chemical deposition; temperature; chelating agent; optical
17	properties

19 **1. Introduction**

20 Copper sulfides (Cu_xS, x = 1-2) are significant binary compounds that attract much 21 attention due to their wide range of applications in optical and electrical devices, such 22 as photo thermal conversion, microwave shielding coatings, solar control coatings, dye-sensitized solar cells, potential nanometer-scale switch, cathode materials in
lithium rechargeable batteries and some chemical sensors [1-4]. Additionally, it has
recently been reported that CuS can transform into a superconductor below the 1.6 K
because of its metallic conduction property [5].

Even though physical techniques are very suitable for synthesizing uniform and high 27 28 quality films, they are very expensive and consume large amounts of energy. On the 29 other hand, chemical methods are economical and suitable for maintaining desired 30 structures. Thus, to prepare CuS thin films with desired components and structures, 31 many different chemical methods have been developed, such as liquid-liquid 32 interface reaction [6], chemical vapor deposition (CVD) [7], chemical vapor reaction (CVR) [8], electrochemical method [9], successive ionic layer adsorption and reaction 33 34 (SILAR) [10], atomic layer deposition (ALD) [11], spray-ion layer gas reaction (ILGAR) [12], chemical bath deposition (CBD) [13-15], etc. Among them, CBD 35 tends to be a better method to deposit CuS films with desired component, particular 36 37 orientation, and thickness because of the advantages of having a variety of substrates 38 (insulators, semiconductors and metals) for deposition, a-suiting large surface area deposition, simplicity, and lower cost. However, bath solution generally contains Cu 39 40 salt, triethanolamine, thiourea, and large amount of sodium hydroxide and/or ammonia for most cases. With such solution the deposition usually required a 41 significant long time to achieve the enough film thickness. To enhance the deposition 42 43 rate, microwave [16] and thermal [17-19] assistances has been introduced to the CBD. In addition, small amount of other chemical bath solution composition, such as, 44

45	aqueous solutions of copper sulphide and thioacetamide mixed together with chelate
46	agent of acetic acid [15], aqueous solution of copper niktrate, concentrated ethylene
47	glycole (C ₂ H ₆ O ₂), thioacetamide with different pH [19], etc., have been used and
48	verified to be suitable for CBD growth of the CuS film.
49	In this paper, we present (i) fast fabrication of uniform CuS films with a simple
50	CBD; (ii) the effects of chemical bath solution composition and deposition time on
51	the thickness and the optical properties of the deposited films.

53 **2. Experiment method**

54 2.1. Deposition of the film

The starting materials used were all analytic grade chemicals without any further 55 56 processing. The bath solution was composed of 0.01 mole cupric acetate (Cu(CH₃COO)₂.H₂O), 0.015 mole thiourea (SC(NH₂)₂), 80 ml deionized water 57 58 and different amounts of disodium ethylenediamine tetraacetate (EDTA-2Na, $C_{10}H_{14}N_2Na_2O_3$) (0.005, 0.01, and 0.015 mole). The solution was homogenized by 59 60 magnetic stirring for 10 min in a beaker at room temperature. Commercial glass slides were used as a substrate and were ultrasonically cleaned in acetone and methanol 61 62 respectively for 0.5 h. At room temperature (~ 20 °C), the film deposited for 7.5 h was 63 grey white, indicating it can not be CuS crystal phase. However, at 50°C the deposited films are dark brown, which may indicates the formation of CuS crystal phase. 64 65 Therefore the deposition temperature of 50 $^{\circ}$ C was selected. After the solutions were put into a furnace, the furnace was heated from room temperature to 50 °C and 66

67 maintained for 10 min to make actually solution temperature reach to 50 °C. Three 68 glass substrates were then put vertically into each of the three solutions. After 0.5 h, 69 1.0 h, and 1.5 h of deposition, the films were successively taken out from the 70 solutions, and rinsed with deionized water to remove the residual bath solution and 71 loosely adhered CuS particles on the films and then naturally dried in air.

72 2.2. Characterization of the films

The phase and structure of the deposited CuS thin films were identified at room temperature using an X-Ray diffractometer (XRD, CuK_{α 1}, λ =0.15406nm, Model No:

D/Max-2200PC, Rigaku, Japan). The morphology and texture of the films were analyzed using atomic force microscopy (AFM, Model No: SPI3800N, NSK, Japan). The transmittance spectra of the films was determined with an ultraviolet-visible spectrophotometer (Model No: 752N, Feilo, China). The photoluminescence spectrum of the films was measured on a photoluminescence spectrophotometer (Model no: F-4600, Hitachi, Japan).

81

82 **3. Results and discussion**

Figure 1 shows the XRD patterns of the CuS films. The main phase of the films was hexagonal covellite CuS (JCPDS: 05-0464). The peak at 2θ ~18° was identified as yarrowite Cu₂S (JCPDS: 36-0379) which decreased with the increase in deposition time and disappeared when the deposition time was 1.5 h. This could be due to CuS is formed at initial stage of the film deposition and covered by CuS with films further deposition. 89 The chemical process for the CuS film formation can be given by:

91
$$SC(NH_2)_2 + 2H_2O \xrightarrow{50 \ ^{\circ}C} 2NH_4^+ + CO_2 + S^{2-}$$
 (2)

92
$$EDTA-Cu+2H_2O = EDTA^{2-}+Cu^{2+}+2H_2O$$
 (3)

93
$$Cu^{2+}+S^{2-}=CuS$$
 (4)

CuS has a very small solubility constant ($K_{sp}=1.27 \times 10^{-36}$) and so is easily formed from the Cu²⁺ and S²⁻ ions in the aqueous solution and very stability in aqueous environment. However, the Cu²⁺ can be chelated with EDTA, so the release rate of Cu²⁺ from the chelate compound EDTA-Cu could control the formation rate of the CuS. Higher temperature can speeds up this release rate and the film deposition.

Figure 2 shows AFM micrographs of the CuS films deposited with EDTA-2Na/Cu²⁺ 99 =1.0. The each films were-was composed of uniform particles. With increasing 100 101 be rodlike. The thickness of the films determined from AFM analysis are shown in 102 103 Fig. 3. The thickness increased as increase in deposition time, which can be ascribed 104 105 Moreover, the deposition rate also shows a maximum at the moderate molar ratio of EDTA-2Na/Cu²⁺=1.0. At lower molar ratio of EDTA-2Na/Cu²⁺=0.5, excessive Cu²⁺ 106 107 antion cation in the solution led to the formation of CuS particle too fast and 108 undesirably large particles formed. Particles with such size have difficulty tightly adhering on the film, which resulted in slower deposition rate of the film. At higher 109 molar ratio of EDTA-2Na/Cu²⁺ =1.5, the release of Cu²⁺ antion cation from the 110

111 EDTA-Cu was slower, and so the deposition rate was lower. As a comparison, a room

temperature CBD deposited CuS films with a thickness of ~470 nm taken ~8 h [16]

113 Figure 4 shows the transmittance spectra of the CuS films fabricated with different 114 EDTA-2Na proportions. The transmittance of the films decreases with increasing the 115 deposition time for each EDTA-2Na proportion. The films fabricated with EDTA-2Na/Cu²⁺=1.0 had the greatest decrease in transmittance with deposition time. 116 117 118 transmittance decreases with deposition time. This is consistent with the increases of 119 the film thicknesses as shown in Fig. 3. However, the decrease in transmission with 120 the deposition time does not seems to be out of scale with the film thickness. This 121 could be mainly attributed to higher transmittance of Cu₂S than CuS [20]. In addition, 122 123

124 CuS is considered as a direct band gap semiconductor, so the relationship between 125 the absorption coefficient (α) near the absorption edge and the optical band gap 126 energy (E_g) for direct band transitions obeys the following formula [21]:

127 $\left(\alpha h \nu\right)^2 = C \left(h \nu - E_g\right)$

where hv is photon energy and C is a constant. the absorption coefficient (α) can be calculated by equation

130 $\alpha = \frac{1}{d} \ln \frac{1}{T}$

where *T* is the transmittance and *d* is the film thickness. Fig. 5 shows the graphs of $(\alpha hv)^2$ vs. photon energy, *hv*, for the CuS thin films. The linear dependence of $(\alpha hv)^2$

133	on hv at higher photon energies indicates that the CuS films are essentially direct-
134	transition-type semiconductors. The straight-line portion of the curve, as extrapolated
135	to zero, gives the optical band gap energy E_g . The estimated E_g was in range of
136	2.59-2.92 eV and decreased with increasing deposition time (Fig. 6). This could be
137	
138	deposition time. As a comparison, Gadave and Lokhande [22] reported optical band
139	gap energies of 2.2 eV and 2.5 eV for CBD and dip coating deposited Cu _x S film.
140	Sartale and Lokhande [23] reported optical band gap energy of 2.36 eV of SILAR
141	deposited Cu _x S from nonaqueous medium. Puspitasari et al [15] reported optical band
142	gap energy of 2.8 eV for the CuS film prepared by a simple chemical method. The
143	variation of the band gap energy with deposition time has been reported by some
144	researcher [16]. They reported that the band gap energy of the CuS film decreased and
145	then increased with microwave-assisted deposition time. The detailed reason for this
146	variation is unclear at present. We believe that the different phases, average particle
147	size, film thickness, crystal orientation, and crystallinities are responsible for this
148	variation.

Figure 7 shows the photoluminescence spectra of the CuS films deposited at the EDTA-2Na/Cu²⁺=1.0. They were measured at excitation wavelength of 350 nm. The emission peaks were centered at ~443 nm. This value is different from that of CuS nanorods (420, 450 and 462 nm [24], and 515 nm [25]) and nanoplates (339 nm [26]).. The emission peaks of ~443 nm corresponded to photon energy of ~2.79 eV that is closed to the band gap energy estimated from the transmittance spectra. This indicated 155 that the emission could come from a near band gap emission. The decrease in the intensity of the emission with the deposition time can be also observed in Fig. 7. Roy 156 157 et al [25] ascribed the decrease in the luminescence intensity of their powders to the 158 increase of particle size due to the decrease in the content of surface oxygen vacancy 159 and defect with increasing the size of materials. In fact, their result indicated that the 160 decrease in the emission intensity was also accompanied by morphology change from 161 nanoparticles to nanorods. Therefore, the decrease in the emission intensity of the 162 CuS films could be associated with the change in the morphology and the crystal 163 orientation (Fig. 1) and the decrease in the particle size of the films.

164

165 **4. Conclusion**

166 CuS semiconductor films were fabricated on a glass substrate in a simple chemical 167 bath solution containing EDTA-2Na as the chelating agent. Thermal assistance was 168 used to accelerate deposition. The effect of EDTA-2Na proportion on the deposition 169 rate and optical properties of the films were investigated, and it was found that the molar ratio of EDTA-2Na/Cu²⁺=1.0 was most effective. At this proportion, the film 170 171 thickness reaches ~541 nm in a relative short deposition time of 1.5 h. Such 172 deposition rate is larger than that produced by usual chemical bath deposition. The 173 optical band gap energy of the films is in range of 2.59-2.92 eV. The films showed 174 the emission peaks centered at ~443 nm. The optical properties have some dependences of microstructure including morphology, particle size and crystal 175 176 orientation. We believe this simple chemical bath deposition technique can be further 177 extended to the fabrication of other semiconductor films.

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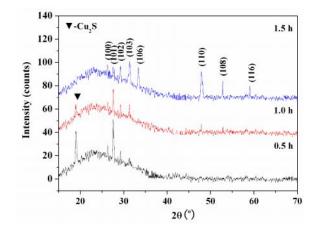
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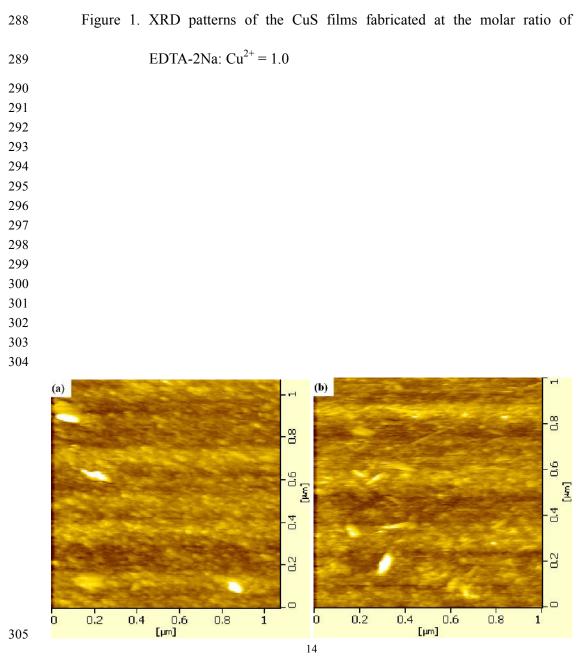
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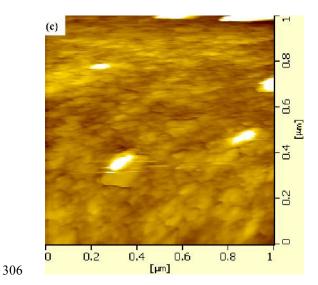


Figure 2. AFM micrographs of the CuS films deposited at molar ratio of EDTA-2Na: $Cu^{2+}=1.0$ for deposition time of (a) 0.5 h, (b) 1.0 h, and (c) 1.5 h

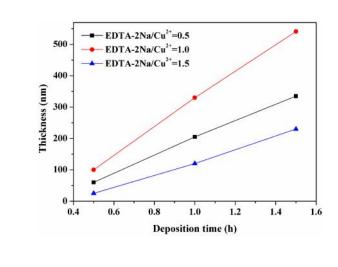
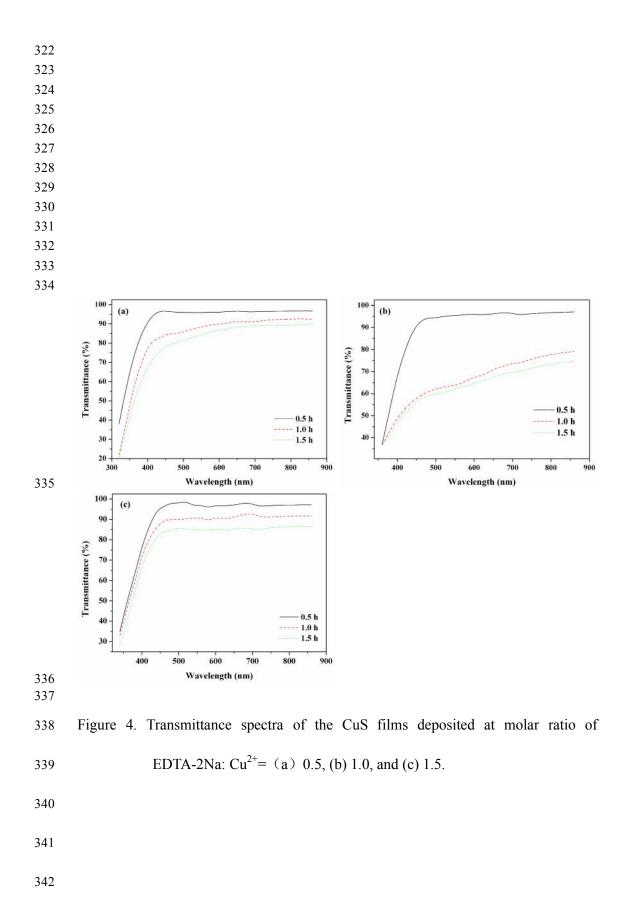
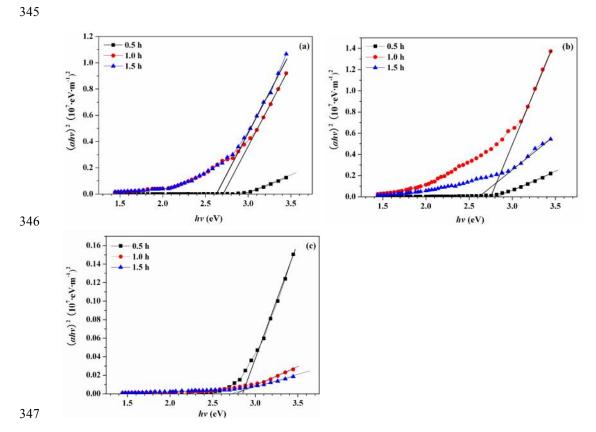


Figure 3 . Film thickness vs. deposition time





348 Figure 5. Plots of $(\alpha hv)^2$ vs. hv of the CuS films deposited at molar ratio of

349 EDTA-2Na:
$$Cu^{2+}=(a)0.5$$
, (b)1.0, and (c)1.5

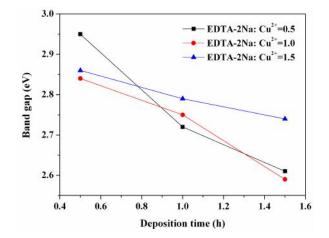


Figure 6 . Optical band gap of the films deposited at at molar ratio of EDTA-2Na: Cu²⁺ as a function of the deposition time

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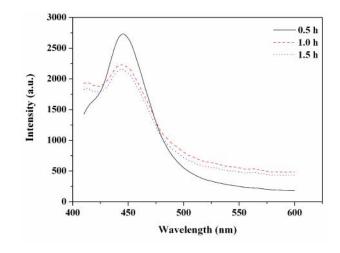




Figure 7. Photoluminescence spectra of the CuS films deposited at EDTA-2Na:

 $Cu^{2+}=1.0$ and excited at excitation wavelength of 350 nm.